

**REMARKS**

In view of the above amendments and the following remarks, reconsideration of the rejections contained in the Office Action of December 20, 2007 is respectfully requested.

By this Amendment, claims 1-20 have been cancelled and new claims 21-38 have been added and are currently pending in the application. No new matter has been added by these amendments.

Revisions have been made to the specification. No new matter has been added by the revisions. Entry of the amendments to the specification is thus respectfully requested.

On page 2 of the Office Action, the Examiner rejected claims 1, 8 and 9 under 35 U.S.C. § 102(b) as being anticipated by Tsuji et al. (US 5,699,027), Ide et al. (US 5,982,077) or Wakabayashi et al. (US 5,585,687). On pages 2-3 of the Office Action, the Examiner rejected claims 2-4, 7, 10-12 and 15-19 under 35 U.S.C. § 103(a) as being unpatentable over Wakabayashi or Ide in view of Tsuji. However, as indicated above, claims 1-20 have been cancelled and replaced with new claims 21-38. For the reasons discussed below, it is respectfully submitted that the new claims are clearly patentable over the prior art of record.

New independent claim 21 includes the limitations of original claims 1 and 2, and recites a piezoelectric resonator element package, comprising a base that holds a piezoelectric resonator element on an internal bottom surface of the base, with the piezoelectric resonator element having drive electrodes formed on front and back sides of the piezoelectric resonator element and being arranged such that one of the drive electrodes is opposed to the internal bottom surface of the base. Claim 21 also recites that the base includes four electrode pads that electrically connect to the drive electrodes of the piezoelectric resonator element, with each of the four electrode pads being formed on a respective corner of the internal bottom surface of the base, and with the four electrode pads consisting of a first electrode pad, a second electrode pad, a third electrode pad, and a fourth electrode pad.

Further, claim 21 recites that the first electrode pad and the second electrode pad are formed along a predetermined side of the internal bottom surface of the base, the first electrode pad and the third electrode pad are formed along one of two sides that are perpendicular to the predetermined side, and that the second electrode pad and the fourth electrode pad are formed

along the other of the two sides that are perpendicular to the predetermined side. Claim 21 also recites that the first electrode pad and the second electrode pad have a different potential, the first electrode pad and the third electrode pad are connected by a first connecting electrode and have a same potential, and that the second electrode pad and the fourth electrode pad are connected by a second connecting electrode and have a same potential.

Further, claim 21 recites avoidance means provided for avoiding electrical connection between at least one of the first and third electrode pads with at least one of the second and fourth electrode pads, with the avoidance means comprising bumps that are formed on the four electrode pads and that are smaller than the electrode pads, and with *at least one of the bumps being formed at a location that does not overlap with the drive electrode that is opposed to the internal bottom surface of the base.*

Tsuji discloses a surface acoustic wave device which, as shown in Fig. 1(a), includes a multilayer substrate 1 having input and output electrodes 4, and grounding electrodes 5 and 6. Tsuji also discloses a surface acoustic wave element 14 having an electrode pad 15 and a comb-shaped electrode 16 on a surface of the surface acoustic wave element 14. Tsuji also discloses a metal bump 11 formed on the electrode pad 15.

However, Tsuji does not disclose avoidance means which includes bumps that are formed on the four electrode pads with *at least one of the bumps being formed at a location that does not overlap with the drive electrode that is opposed to the internal bottom surface of the base*, as required by independent claim 21. Rather, Tsuji discloses that the metal bumps 11 are formed on the electrode pad 15 of the surface acoustic wave element 14, and are arranged to face the input and output electrodes 4 and the grounding electrodes 5, as shown in Fig. 1(a). In other words, Tsuji only discloses bumps which do overlap with the opposing drive electrode because Tsuji discloses that the metal bumps 11 are formed on the electrode pad 15 so as to face the input and output electrodes 4 and the grounding electrode 5 (see column 4, lines 38-51). Therefore, Tsuji does not disclose avoidance means which includes bumps that are formed on the four electrode pads with at least one of the bumps being formed at a location that does not overlap with the drive electrode that is opposed to the internal bottom surface of the base, as required by independent claim 21.

Wakabayashi discloses a piezoelectric oscillator which includes a piezoelectric oscillating reed, an insulating substrate and a cap. However, as noted by the Examiner on page 2 of the Office Action, Wakabayashi does not disclose an avoidance means which includes bumps, as required by independent claim 21.

Similarly, Ide discloses a piezoelectric transducer unit which includes an insulating substrate, a crystal oscillator and a ceramic cap. However, as noted by the Examiner on page 2 of the Office Action, Ide does not disclose an avoidance means which includes bumps, as required by independent claim 21.

Therefore, none of the Tsuji, Wakabayashi and Ide references anticipates independent claim 21, because none of the Tsuji, Wakabayashi and Ide references discloses avoidance means which includes bumps that are formed on the four electrode pads with at least one of the bumps being formed at a location that does not overlap with the drive electrode that is opposed to the internal bottom surface of the base, as required by independent claim 21.

Further, because none of the Tsuji, Wakabayashi and Ide references discloses avoidance means which includes bumps that are formed on the four electrode pads with at least one of the bumps being formed at a location that does not overlap with the drive electrode that is opposed to the internal bottom surface of the base, as required by independent claim 21, the combination of the Tsuji, Wakabayashi and Ide references does not disclose or suggest avoidance means which includes bumps that are formed on the four electrode pads with at least one of the bumps being formed at a location that does not overlap with the drive electrode that is opposed to the internal bottom surface of the base.

Therefore, for the reasons presented above, it is believed apparent that the present invention as recited in independent claim 21 is not disclosed or suggested by the Tsuji reference, the Wakabayashi reference and the Ide reference taken either individually or in combination. Accordingly, a person having ordinary skill in the art would clearly not have modified the Tsuji reference in view of the Wakabayashi reference or the Ide reference in such a manner as to result in or otherwise render obvious the present invention of independent claim 21. Further, it is respectfully submitted that claims 22-33 are similarly patentable at least by virtue of their dependency from claim 21.

In addition, on page 3 of the Office Action, the Examiner indicated that claims 5, 6, 13, 14 and 20 contain allowable subject matter and would be allowed if rewritten in independent form including all the limitations of the base claim and any intervening claims. In this regard, it is noted that new independent claim 34 includes the limitations of base claim 1 and allowable claim 5. Therefore, in view of the Examiner's indication of the allowability of original claim 5, it is respectfully submitted that independent claim 34 is clearly patentable over the prior art of record.

Further, it is noted that new dependent claims 35-38 correspond to allowable claims 6, 14, 13 and 20, respectively. Thus, in view of the Examiner's indication of the allowability of claims 6, 13, 14 and 20, it is respectfully submitted that dependent claims 35-38 are also in condition for allowance.

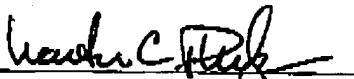
Therefore, it is respectfully submitted that independent claims 21 and 34, as well as claims 22-33 and 35-38 which depend therefrom, are clearly allowable over the prior art of record.

In view of the foregoing amendments and remarks, it is respectfully submitted that the present application is clearly in condition for allowance. An early notice to that effect is respectfully solicited.

If, after reviewing this Amendment, the Examiner feels there are any issues remaining which must be resolved before the application can be passed to issue, the Examiner is respectfully requested to contact the undersigned by telephone in order to resolve such issues.

Respectfully submitted,

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